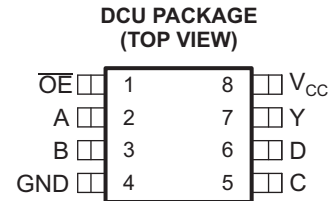


具有三态输出的超级可配置多功能门

 查询样品: [SN74LVC1G99-Q1](#)

特性

- 符合汽车应用要求
- 支持 **5 V V_{CC}** 工作
- 允许接受输入电压: **5.5 V**
- 低功耗, 最大 **15- μ A I_{CC}**
- **3.3 V** 电压下 **\pm 24 mA** 的输出驱动器
- 在一个封装内提供**9**个不同的逻辑功能
- **I_{off}** 支持部分断电模式工作
- 输入滞后允许慢速输入转换时间和更好的输入端抗噪性



说明/订购信息

SN74LVC1G99-Q1运行在电压值1.65 V 到 5.5 V之间。

SN74LVC1G99-Q1 具备拥有3态输出的可配置多重功能。当输出使能 ($\overline{\text{OE}}$) 输入为高电平时, 输出被停用。当 $\overline{\text{OE}}$ 值较低时, 输出状态由4位输入的16个模式确定。用户可以选择逻辑功能, 例如 MUX, AND, OR, NAND, NOR, XOR, XNOR, 反相器, 和缓冲器。所有输入可被连接到 V_{CC} 或者 GND。

这个设备的功能是独立反相器, 但是由于施密特作用(双稳态电路作用), 对于正向 (V_{T+}) 和负向 (V_{T-}) 信号, 它有不同输入阈值水平。

为了确保上电或断电期间的高阻抗状态, $\overline{\text{OE}}$ 应通过一个上拉电阻器连接至 V_{CC}: 该电阻器的最小值由驱动器的电流吸收能力来决定。

该器件的技术规格针对采用 I_{off} 的部分断电应用而全面拟订。I_{off} 电路可禁用输出, 能够防止在器件断电时电流回流对器件造成损坏。

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾ ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
-40°C to 125°C	VSSOP – DCU	Reel of 3000	SN74LVC1G99QDCURQ1	CAZ_

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(3) DCU: The actual top-side marking has one additional character that designates the assembly/test site.

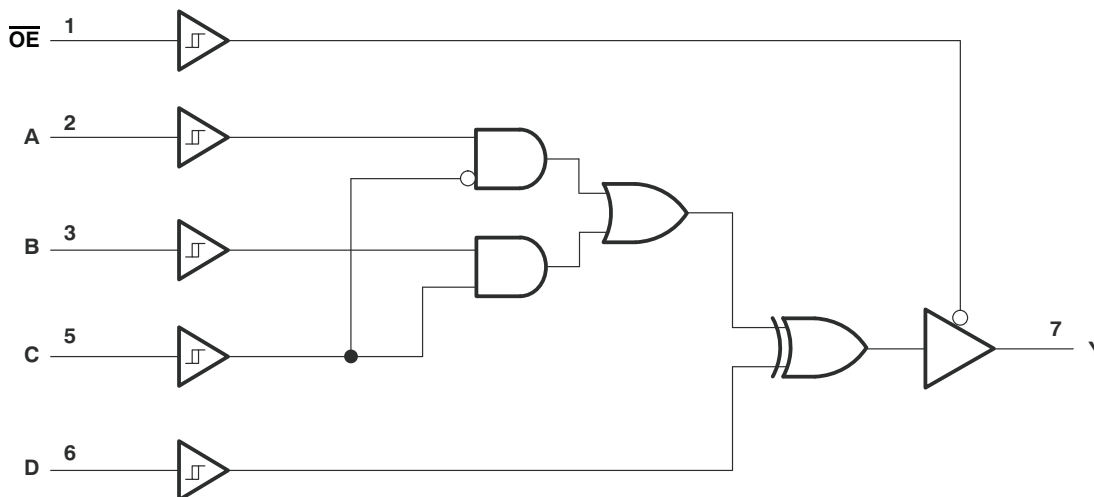


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FUNCTION TABLE

INPUTS					OUTPUT
$\overline{\text{OE}}$	D	C	B	A	Y
L	L	L	L	L	L
L	L	L	L	H	H
L	L	L	H	L	L
L	L	L	H	H	H
L	L	H	L	L	L
L	L	H	L	H	L
L	L	H	H	L	H
L	L	H	H	H	H
L	H	L	L	L	H
L	H	L	L	H	L
L	H	L	H	L	H
L	H	L	H	H	L
L	H	H	L	L	H
L	H	H	L	H	H
L	H	H	H	L	L
L	H	H	H	H	L
H	H or L	H or L	H or L	H or L	Z

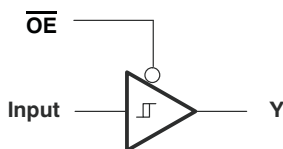
LOGIC DIAGRAM (POSITIVE LOGIC)



FUNCTION SELECTION TABLE

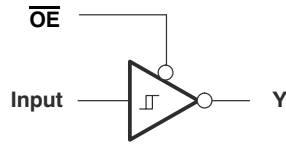
PRIMARY FUNCTION	COMPLEMENTARY FUNCTION	PAGE
3-state buffer		3
3-state inverter		3
3-state 2-in-1 data selector MUX		4
3-state 2-in-1 data selector MUX, inverted out		4
3-state 2-input AND	3-state 2-input NOR, both inputs inverted	5
3-state 2-input AND, one input inverted	3-state 2-input NOR, one input inverted	5
3-state 2-input AND, both inputs inverted	3-state 2-input NOR	5
3-state 2-input NAND	3-state 2-input OR, both inputs inverted	6
3-state 2-input NAND, one input inverted	3-state 2-input OR, one input inverted	6
3-state 2-input NAND, both inputs inverted	3-state 2-input OR	6
3-state 2-input XOR		7
3-state 2-input XNOR	3-state 2-input XOR, one input inverted	7

3-STATE BUFFER FUNCTIONS AVAILABLE



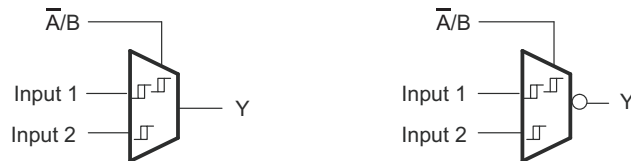
FUNCTION	\overline{OE}	A	B	C	D
3-state buffer	L	Input	H or L	L	L
		H or L	Input	H	L
		L	H	Input	L
		H	L	Input	H
		H	H or L	L	Input
		H or L	L	H	Input
		L	L	H or L	Input

3-STATE INVERTER FUNCTIONS AVAILABLE



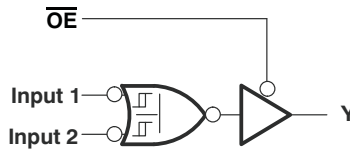
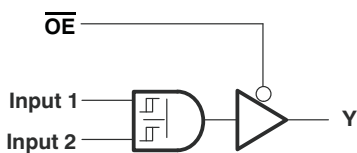
FUNCTION	\overline{OE}	A	B	C	D
3-state buffer	L	Input	H or L	L	H
		X	Input	H	H
		L	H	Input	H
		H	L	Input	L
		H	H or L	L	Input
		H or L	H	H	Input
		H	H	H or L	Input

3-STATE MUX FUNCTIONS AVAILABLE

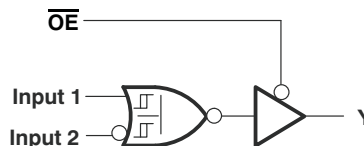
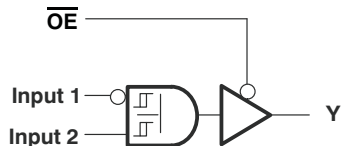


FUNCTION	\overline{OE}	A	B	C	D
3-state 2-to-1, data selector MUX	L	Input 1	Input 2	$\overline{\text{Input 1}}$ or Input 2	L
3-state 2-to-1, data selector MUX		Input 2	Input 1	$\overline{\text{Input 2}}$ or Input 1	L
3-state 2-to-1, data selector MUX, inverted out		Input 1	Input 2	$\overline{\text{Input 1}}$ or Input 2	H
3-state 2-to-1, data selector MUX, inverted out		Input 2	Input 1	$\overline{\text{Input 2}}$ or Input 1	H

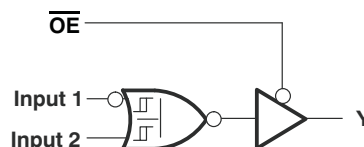
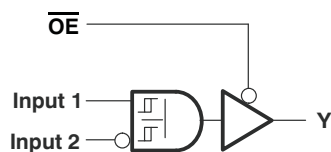
3-STATE AND/NOR/OR FUNCTIONS AVAILABLE



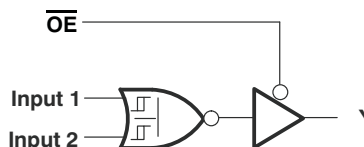
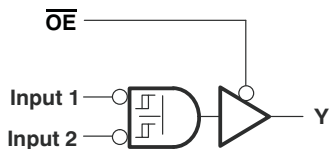
NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state AND	3-state NOR	L	L	Input 1	Input 2	L
2	3-state AND	3-state NOR		L	Input 2	Input 1	L



NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state AND	3-state NOR	L	Input 2	L	Input 1	L
2	3-state AND	3-state NOR		H	Input 1	Input 2	H

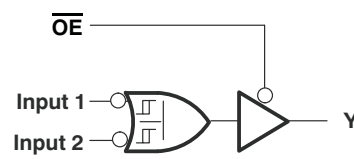
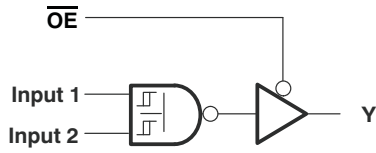


NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state AND	3-state NOR	L	Input 1	L	Input 2	L
2	3-state AND	3-state NOR		H	Input 2	Input 1	H

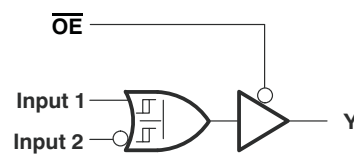
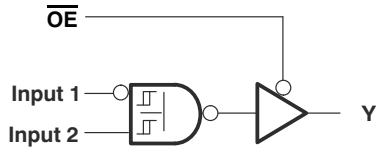


NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state AND, both inverted inputs	3-state NOR	L	Input 1	H	Input 2	H
2	3-state AND, both inverted inputs	3-state NOR		Input 2	H	Input 1	H

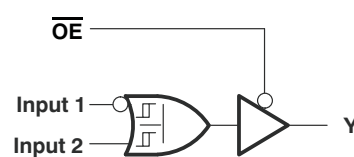
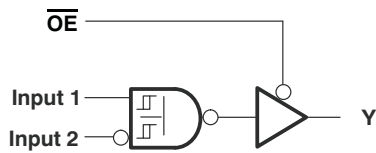
3-STATE NAND/OR FUNCTIONS AVAILABLE



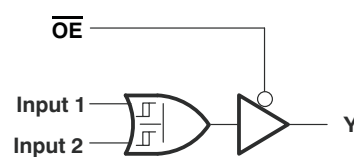
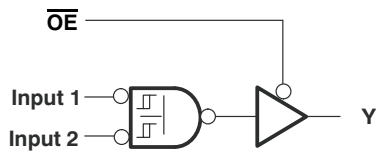
NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state NAND	3-state OR	L	L	Input 1	Input 2	H
2	3-state NAND	3-state OR		L	Input 2	Input 1	H



NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state NAND	3-state OR	L	Input 2	L	Input 1	H
2	3-state NAND	3-state OR		H	Input 1	Input 2	L

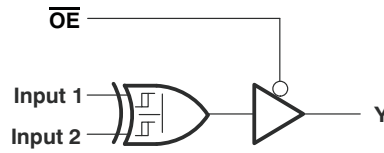


NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state NAND	3-state OR	L	Input 1	L	Input 2	H
2	3-state NAND	3-state OR		H	Input 2	Input 1	L

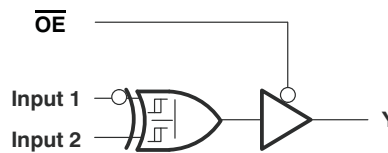


NO. OF INPUTS	AND/NAND FUNCTION	OR/NOR FUNCTION	\overline{OE}	A	B	C	D
2	3-state NAND	3-state OR	L	Input 1	H	Input 2	L
2	3-state NAND	3-state OR		Input 2	H	Input 1	L

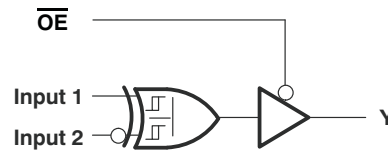
3-STATE XOR/XNOR FUNCTIONS AVAILABLE



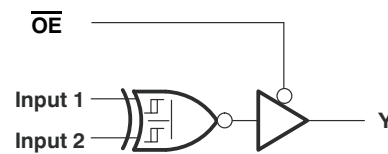
FUNCTION	\overline{OE}	A	B	C	D
3-state XOR	L	Input 1	H or L	L	Input 2
		Input 2	H or L	L	Input 1
		H or L	Input 1	H	Input 2
		H or L	Input 2	H	Input 1
		L	H	Input 1	Input 2
		L	H	Input 2	Input 1



FUNCTION	\overline{OE}	A	B	C	D
3-state XOR	L	H	L	Input 1	Input 2



FUNCTION	\overline{OE}	A	B	C	D
3-state XOR	L	H	L	Input 1	Input 2



FUNCTION	\overline{OE}	A	B	C	D
3-state XNOR	L	H	L	Input 1	Input 2
3-state XNOR		H	L	Input 2	Input 1

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V _{CC}	Supply voltage range	-0.5	6.5	V	
V _I	Input voltage range ⁽²⁾	-0.5	6.5	V	
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V	
V _O	Voltage range applied to any output in the high or low state ^{(2) (3)}	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0	-50	mA	
I _{OK}	Output clamp current	V _O < 0	-50	mA	
I _O	Continuous output current		±50	mA	
	Continuous current through V _{CC} or GND		±100	mA	
θ _{JA}	Package thermal impedance ⁽⁴⁾	DCU package	227	°C/W	
T _{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT	
V _{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V _I	Input voltage	0	5.5	V	
V _O	Output voltage	0	V _{CC}	V	
I _{OH}	High-level output current	V _{CC} = 1.65 V		-4	mA
		V _{CC} = 2.3 V		-8	
		V _{CC} = 3 V		-16	
		V _{CC} = 4.5 V		-24	
I _{OL}	Low-level output current	V _{CC} = 1.65 V		4	mA
		V _{CC} = 2.3 V		8	
		V _{CC} = 3 V		16	
		V _{CC} = 4.5 V		24	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	ns/V
		V _{CC} = 3.3 V ± 0.3 V		10	
		V _{CC} = 5 V ± 0.5 V		5	

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{T+} Positive-going input threshold voltage		1.65 V	0.79		1.26	V
		2.3 V	1.11		1.66	
		3 V	1.5		1.97	
		4.5 V	2.16		2.84	
		5.5 V	2.61		3.43	
V _{T-} Negative- going input threshold voltage		1.65 V	0.39		0.72	V
		2.3 V	0.58		0.97	
		3 V	0.84		1.24	
		4.5 V	1.41		1.89	
		5.5 V	1.87		2.39	
ΔV _T Hysteresis (V _{T+} – V _{T-})		1.65 V	0.37		0.72	V
		2.3 V	0.48		0.87	
		3 V	0.56		0.97	
		4.5 V	0.71		1.14	
		5.5 V	0.71		1.21	
V _{OH}	I _{OH} = –100 μA	1.65 V to 5.5 V	V _{CC} – 0.1			V
	I _{OH} = –4 mA	1.65 V	1.2			
	I _{OH} = –8 mA	2.3 V	1.9			
	I _{OH} = –16 mA	3 V	2.4			
	I _{OH} = –24 mA		2.3			
	I _{OH} = –32 mA	4.5 V	3.8			
V _{OL}	I _{OL} = 100 μA	1.65 V to 5.5 V			0.1	V
	I _{OL} = 4 mA	1.65 V			0.45	
	I _{OL} = 8 mA	2.3 V			0.35	
	I _{OL} = 16 mA	3 V			0.45	
	I _{OL} = 24 mA				0.55	
	I _{OL} = 32 mA	4.5 V			0.60	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±5	μA
I _{off}	V _I or V _O = 5.5 V	0 V			±10	μA
I _{OZ}	V _O = V _{CC} or GND	1.65 V to 5.5 V			±10	μA
I _{CC}	V _I = 5.5 V or GND, I _O = 0	1.65 V to 5.5 V			15	μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V			500	μA
C _i	V _I = V _{CC} or GND	3.3 V	3.5			pF
C _o	V _O = V _{CC} or GND	3.3 V	6			pF

(1) T_A = 25°C

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 30$ pF or 50 pF (unless otherwise noted) (see [Figure 1](#))

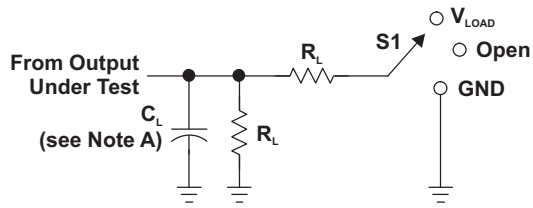
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 5\text{ V}$ $\pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	4.6	32.8	2.6	13.7	2.4	10.4	1.8	6.9	ns
	B		4.6	30.9	2.6	13.3	2.3	10.2	1.8	6.8	
	C		4.4	31.8	2.5	14.3	2.5	10.6	1.8	7.2	
	D		4.3	27.7	2.5	12.7	2.4	9.6	1.6	6.5	
t_{en}	\overline{OE}	Y	4.2	27.2	2.4	13.3	2	9	1.7	6.0	ns
t_{dis}	\overline{OE}	Y	3.7	17	2	7.3	2.1	7.4	1	5.6	ns

OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	$V_{CC} = 5\text{ V}$	UNIT
		TYP	TYP	TYP	TYP	
C_{pd} Power dissipation capacitance	$f = 10\text{ MHz}$	19	20	22	27	pF

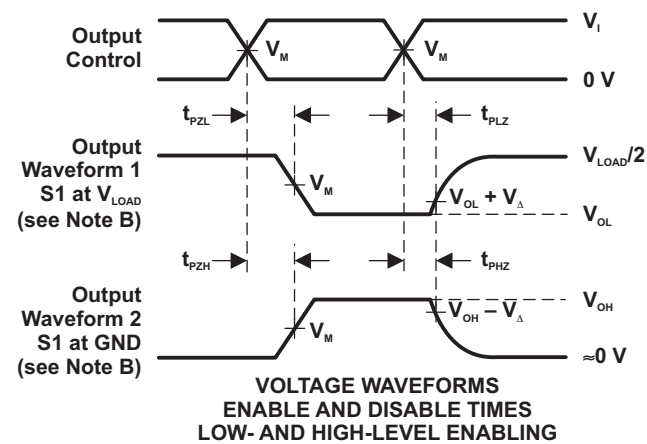
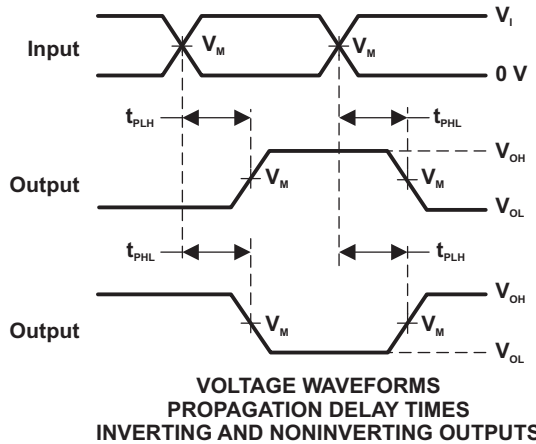
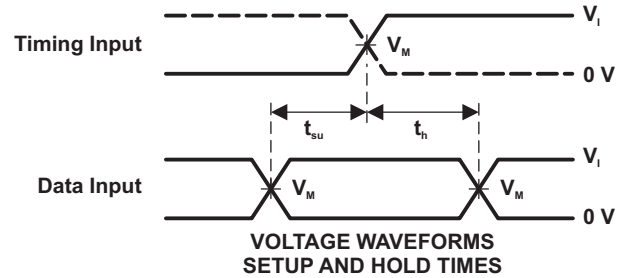
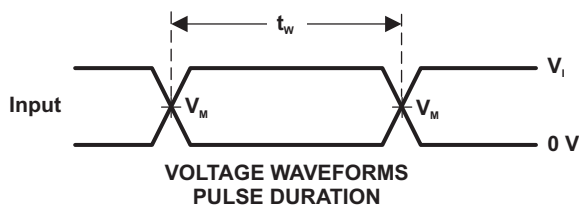
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_i/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	V_{CC}	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_o = 50\ \Omega$.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC1G99QDCURQ1	ACTIVE	VSSOP	DCU	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CAZR	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



4225266/A 09/2014

NOTES:

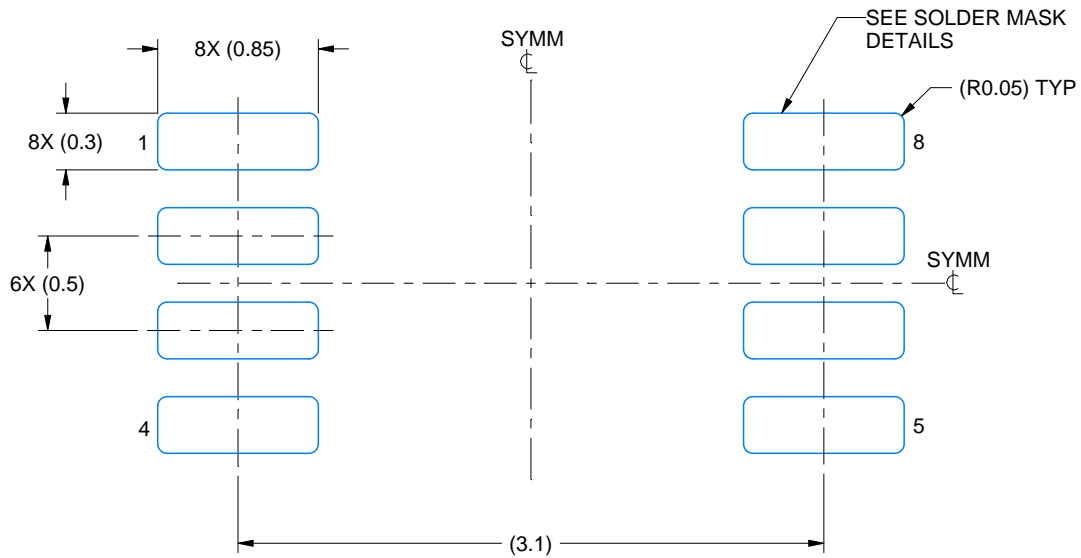
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-187 variation CA.

EXAMPLE BOARD LAYOUT

DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 25X



4225266/A 09/2014

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 25X

4225266/A 09/2014

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2023，德州仪器 (TI) 公司